

Economy Power 2.5

TE Internal #: 2317374-1

PCB Mount Header, Vertical, Wire-to-Board, 4 Position, 2.5 mm Centerline, Fully Shrouded, Tin, Through Hole - Solder, Signal,

Economy Power 2.5

View on TE.com >



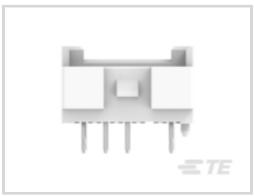
Connectors > PCB Connectors > PCB Headers & Receptacles











PCB Connector Assembly Type: PCB Mount Header

Connector System: Wire-to-Board

Number of Positions: 4

Number of Rows: 1

Centerline (Pitch): 2.5 mm

Features

Product Type Features

Trouber Type I data see	
PCB Connector Assembly Type	PCB Mount Header
Connector System	Wire-to-Board
Header Type	Fully Shrouded
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
Configuration Features	
Number of Positions	4
Number of Rows	1
PCB Mount Orientation	Vertical
Body Features	
Primary Product Color	Natural
Contact Features	
Mating Pin Diameter	.6 mm[.024 in]

Nickel

Contact Underplating Material



Contact Mating Area Plating Material	Tin
Contact Type	Pin
Contact Current Rating (Max)	4.2 A
Termination Features	
Termination Post & Tail Diameter	.6 mm[.024 in]
Termination Method to PCB	Through Hole - Solder
Mechanical Attachment	
Mating Alignment Type	Polarization
Mating Retention	Without
Connector Mounting Type	Board Mount
Mating Alignment	With
PCB Mount Alignment	With
PCB Mount Retention	Without
Housing Features	
Housing Material	Nylon
Centerline (Pitch)	2.5 mm
Usage Conditions	
Operating Temperature Range	-55 – 105 °C[-67 – 221 °F]
Operation/Application	
Circuit Application	Signal
Industry Standards	
UL Flammability Rating	UL 94V-0
Packaging Features	

Product Compliance

Packaging Method

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2024 (241)

Bag, Box



	Candidate List Declared Against: JUNE 2024 (241) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Wave solder capable to 265°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts











Also in the Series | Economy Power 2.5





Connector Contacts(6)



Connector Hardware(49)



PCB Headers & Receptacles(537)



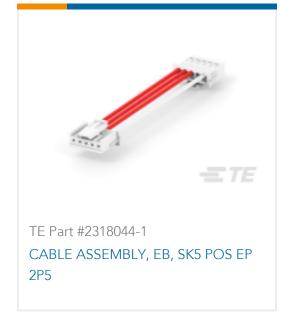
Wire-to-Board Connector Assemblies & Housings(305)

Customers Also Bought









Documents

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_2317374-1_A.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_2317374-1_A.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_2317374-1_A.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use

Product Specifications

Application Specification

English